

ABSTRACT**SEMICONDUCTOR MULTI-PACKAGE MODULE HAVING
PACKAGE STACKED OVER DIE-DOWN FLIP CHIP BALL GRID ARRAY PACKAGE
AND HAVING WIRE BOND INTERCONNECT BETWEEN STACKED PACKAGES**

A semiconductor multi-package module having stacked second and first packages, each package including a die attached to a substrate, in which the first and second package substrates are interconnected by wire bonding, and in which the first package is a flip chip ball grid array package in a die-down configuration. Also, a method for making a semiconductor multi-package module, by providing a first package including a first package substrate and having a die-down flip chip configuration, affixing a second package including a second package substrate an upper surface of the first package, and forming z-interconnects between the first and second package substrates.